

P-Channel Enhancement MOSFET

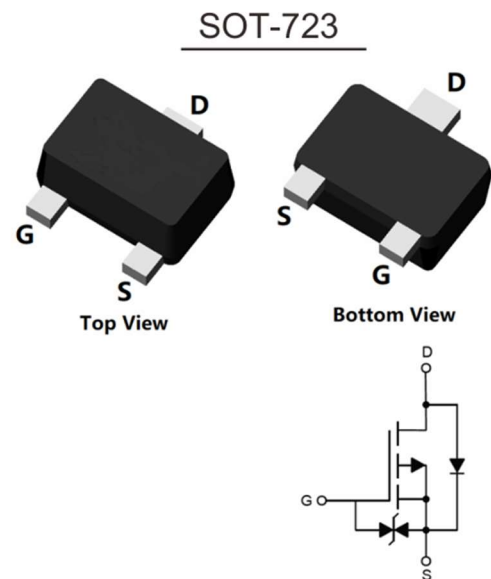
Features

- Trench Power MV MOSFET technology
- Extremely low switching loss
- Excellent stability and uniformity
- Halogen-Free & Lead-Free
- ESD Protected up to 2KV (HBM)

Product Summary		
V _{DS}	R _{DS(on)} (Ω) Typ	I _D (A)
-20V	0.65@ -4.5V -0.5A	-0.5
	0.9@ -2.5V -0.3A	

Application

- Load Switch for Portable Devices
- Voltage controlled small signal switch



Absolute Maximum Ratings (at T_A = 25°C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	-20	V	
Gate-Source Voltage	V _{GS}	±10	V	
Continuous Drain Current	T _A = 25°C	I _D	-0.5	A
	T _A = 70°C	I _D	-0.3	A
Peak Drain Current, Pulsed ¹⁾	I _{DM}	-2.5	A	
Power Dissipation	T _A = 25°C	P _D	0.28	W
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55~150	°C	

Thermal Characteristics

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient ²⁾	R _{θJA}	450	°C/W

Note:

1) Pulse width ≤300us, duty cycle ≤2%, limited by T_J max.

2) Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

Characteristics at T_J = 25°C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
STATIC PARAMETERS					
Drain-Source Breakdown Voltage at V _{GS} =0V, I _D =-250μA	BV _{DSS}	-20			V
Drain-Source Leakage Current at V _{DS} =-20V, V _{GS} =0V	I _{DSS}			-1	μA
Gate Leakage Current at V _{GS} =±10V, V _{DS} =0V	I _{GSS}			±10	μA
Gate-Source Threshold Voltage at V _{DS} =V _{GS} , I _D =-250μA	V _{GS(th)}	-0.35	-0.7	-1.1	V
Drain-Source On-State Resistance at V _{GS} = -4.5V, I _D = -0.5A at V _{GS} = -2.5V, I _D = -0.3A at V _{GS} = -1.8V, I _D = -0.2A	R _{DS(on)}		0.65 0.9 1.4	0.85 1.2 2	Ω
DYNAMIC PARAMETERS					
Input Capacitance at V _{GS} =0V, V _{DS} =-10V, f=1MHz	C _{iss}		40		pF
Output Capacitance at V _{GS} =0V, V _{DS} =-10V, f=1MHz	C _{oss}		15		
Reverse Transfer Capacitance at V _{GS} =0V, V _{DS} =-10V, f=1MHz	C _{rss}		10		
Gate charge total at V _{DS} =-10V, V _{GS} =-4.5V, I _D =-0.5A	Q _g		1.24		nC
Gate to Source Charge at V _{DS} =-10V, V _{GS} =-4.5V, I _D =-0.5A	Q _{gs}		0.37		
Gate to Drain Charge at V _{DS} =-10V, V _{GS} =-4.5V, I _D =-0.5A	Q _{gd}		0.27		
Turn-On Delay Time at V _{DD} =-10V, V _{GS} =-4.5V, R _{GEN} =3Ω, I _D =-0.5A	t _{d(on)}		4		nS
Turn-On Rise Time at V _{DD} =-10V, V _{GS} =-4.5V, R _{GEN} =3Ω, I _D =-0.5A	t _r		19		
Turn-Off Delay Time at V _{DD} =-10V, V _{GS} =-4.5V, R _{GEN} =3Ω, I _D =-0.5A	t _{d(off)}		16		
Turn-Off Fall Time at V _{DD} =-10V, V _{GS} =-4.5V, R _{GEN} =3Ω, I _D =-0.5A	t _f		25		
Reverse Recovery Time at I _S =-0.5A, di/dt=100A/μs	t _{rr}		26		nS
Reverse Recovery Charge at I _S =-0.5A, di/dt=100A/μs	Q _{rr}		0.97		nC
Body-Diode PARAMETERS					
Drain-Source Diode Forward Voltage at I _S =-0.5A, V _{GS} =0V	V _{SD}			-1.2	V
Maximum Body-Diode Continuous Current	I _S			-0.5	A

Electrical Characteristics Curves

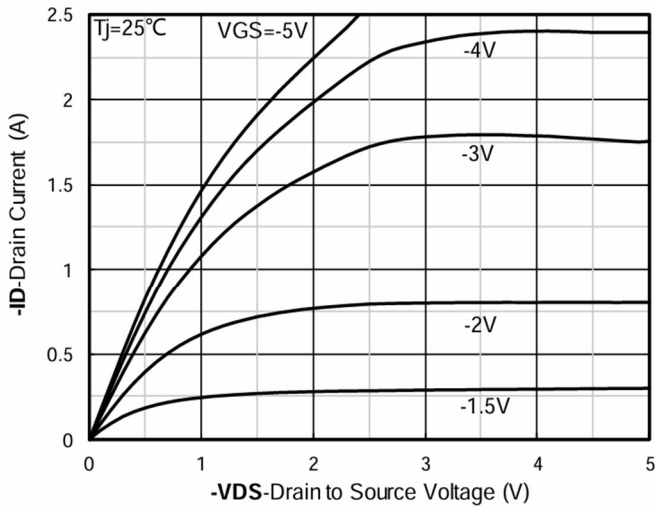


Figure 1. Output Characteristics

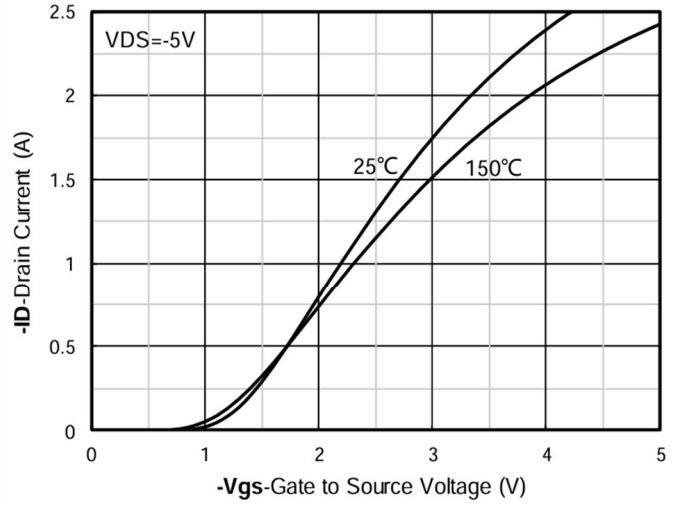


Figure 2. Transfer Characteristics

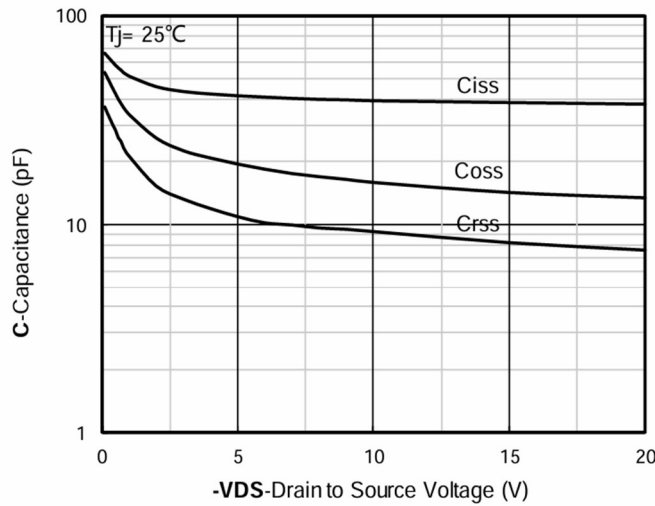


Figure 3. Capacitance Characteristics

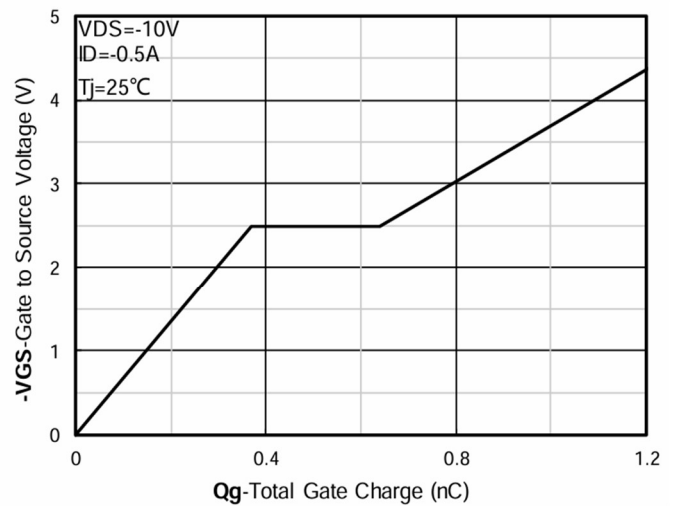


Figure 4. Gate Charge

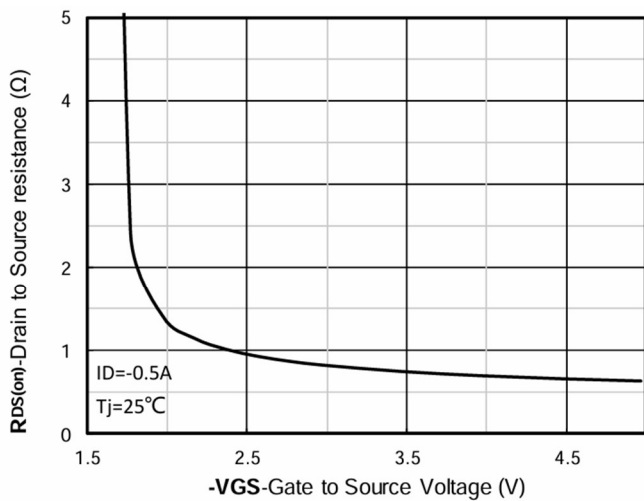


Figure 5. On-Resistance vs Gate to Source Voltage

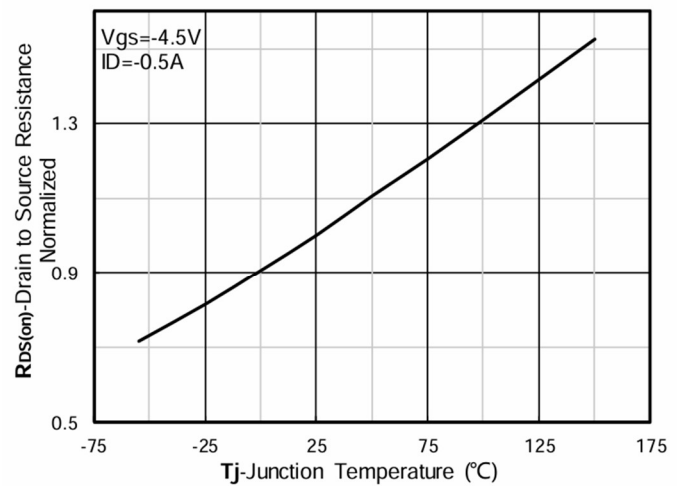
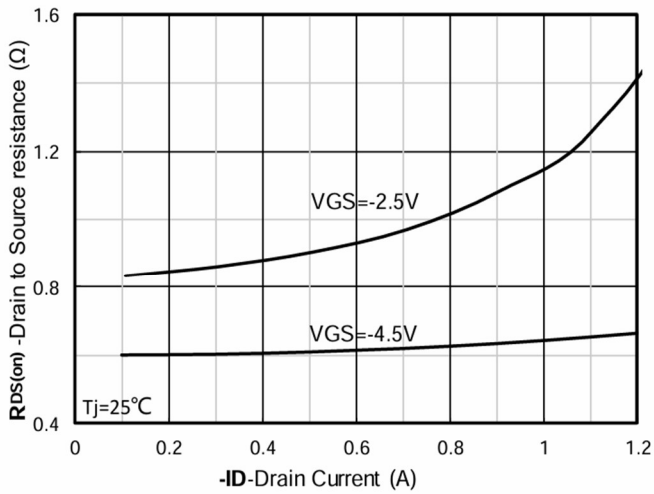
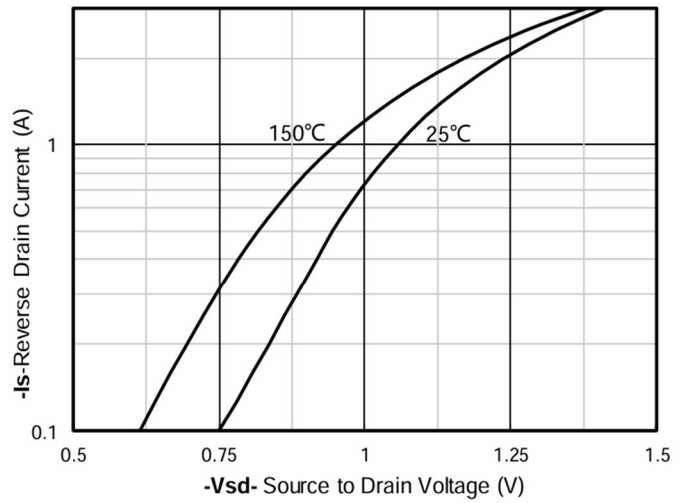


Figure 6. Normalized On-Resistance

Electrical Characteristics Curves



7. RDS(on) VS Drain Current



8. Forward characteristics of reverse diode

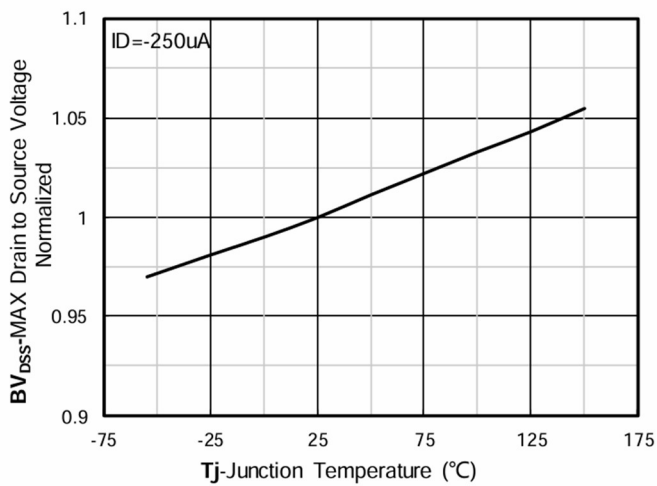


Figure 9. Normalized breakdown voltage

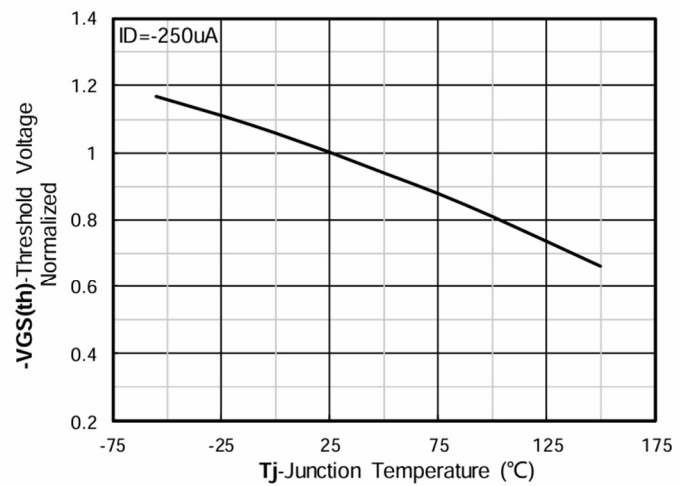


Figure 10. Normalized Threshold voltage

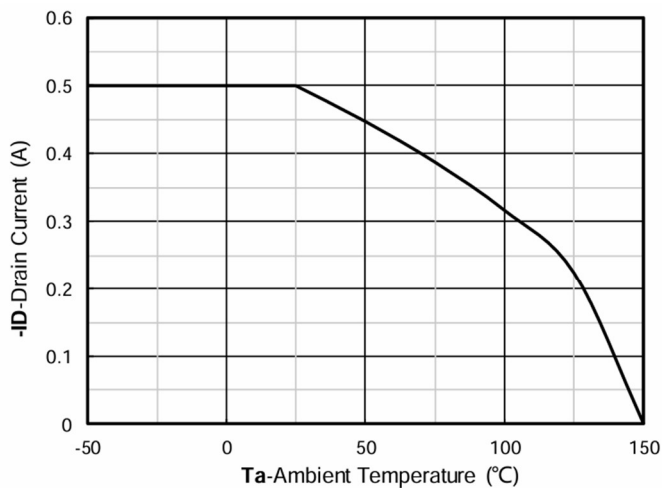


Figure 11. Current dissipation

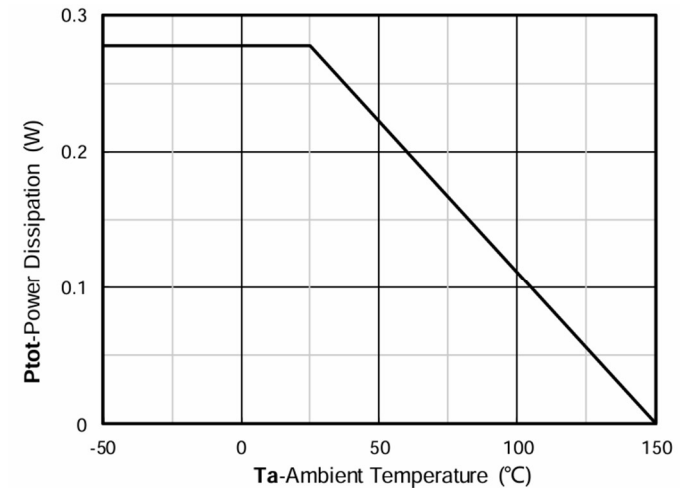


Figure 12. Power dissipation

Electrical Characteristics Curves

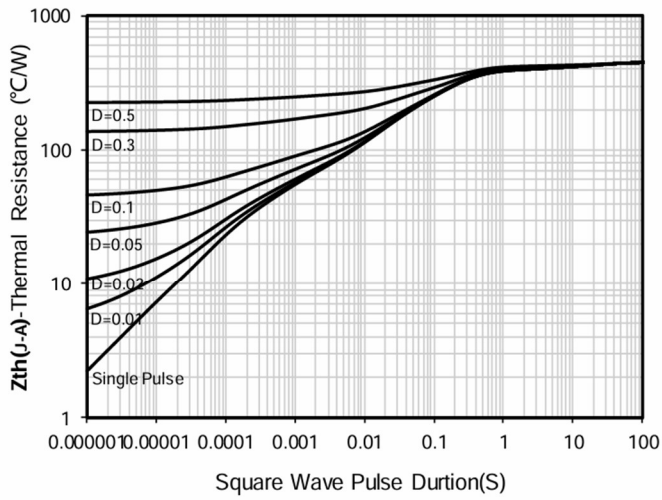


Figure 13. Maximum Transient Thermal Impedance

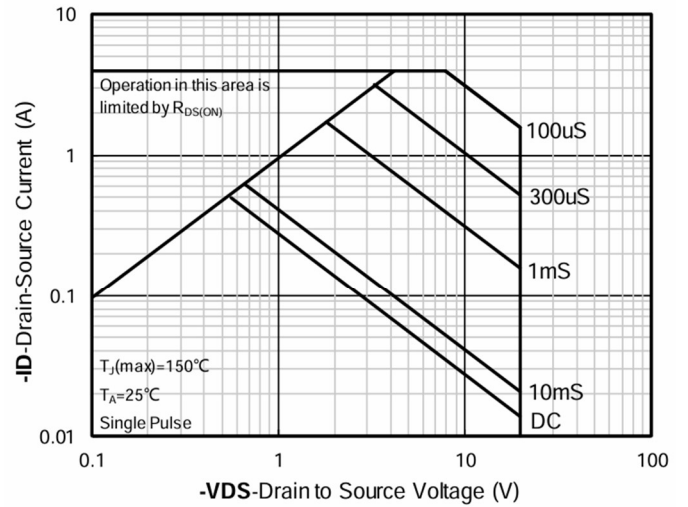
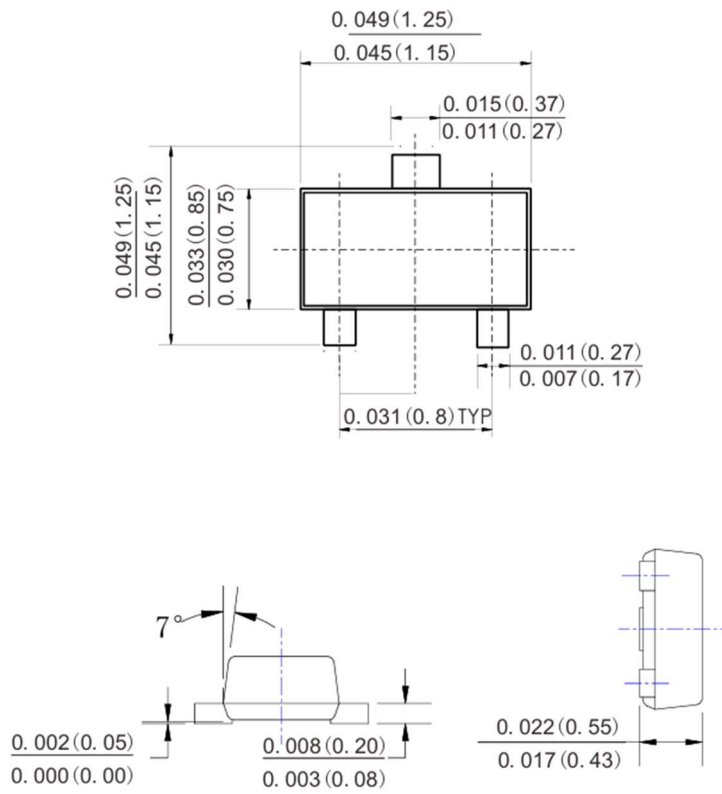


Figure 14. Safe Operation Area

Order Information

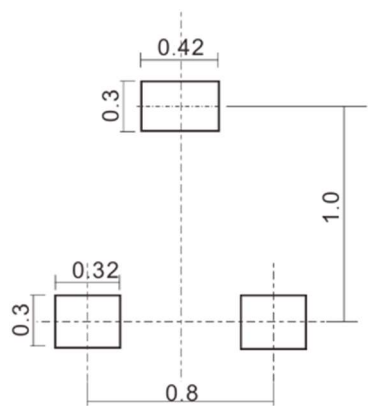
Part Number	Package	Marking	Quantity
Sh3139KAT	SOT-723	KA	3000

Package Outline Dimensions (Units: mm) SOT-723



Dimensions in inches and (millimeters)

Suggested Pad Layout



Dimensions in millimeters